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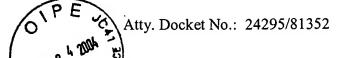
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PTO/SB/21 (08-03)
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TRANSMITTAL			Application Number	10/608,613	
			Filing Date	June 27, 2003	
FORM			First Named Inventor	Adrian E. Ong	
(to be used for all correspondence after initial filing)			Art Unit	2829	
			Examiner Name	Tung X. Nguyen	
Total Number of Pages in This Submission 4			Attorney Docket Number	24295/81352	
ENCLOSURES (check all that apply)					
Fee Transmittal form  Fee Attached  Amendment / Reply  After Final  Affidavits/declaration(s)  Extension of Time Request  Express Abandonment Request  Information Disclosure Statement  Certified Copy of Priority Document(s)		Petit Prov Chai	ving(s)  nsing-related Papers  tion  tion to Convert a risional Application er of Attorney, Revocation nge of Correspondence  ninal Disclaimer  uest for Refund  Number of CD(s)		After Allowance communication to Group Appeal Communication to Board of Appeals and Interferences Appeal Communication to Group (Appeal Notice, Brief, Reply Brief) Proprietary Information Status Letter Other Enclosure(s) (please identity below): Return Receipt Postcard
Response to Missing Parts/ Incomplete Application  Response to Missing Parts under 37 CRF 1.52 or 1.53			J		
SIGNATURE OF APPLICANT, ATTORNEY, OR AGENT					
Firm or Individual Name Philip W. Woo, Reg. No. 39,880  Signature  Date September 24, 2004					
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1

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Adrian E. Ong

Title:

Bonding Pads for Testing of a Semiconductor Device

Application No.:

10/608,613

Filing Date:

June 27, 2003

Examiner:

Tung X. Nguyen

Group Art Unit:

2829

Confirmation No.:

2220

Law Office:

Sidley Austin Brown & Wood LLP

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

## **RESPONSE TO OFFICE ACTION**

Dear Sir:

This is a response to the Office Action dated August 24, 2004, which requires a restriction election to be made between the following groups of claims:

Group I: Claims 1-28, drawn to a system for testing a first integrated circuit chip to be packaged along with at least a second integrated circuit chip in a semiconductor, classified in class 324, subclass 765.

Group II: Claims 29-32, drawn to an integrated circuit chip, classified in class 324, subclass 158.1.